

SPECIFICATIONS CL30G3D

OUTLINES DIMENSIONS

Description

*Round Type

*T1 (3mm) Diameter

*Lens Color: Green Diffused

*With Flange

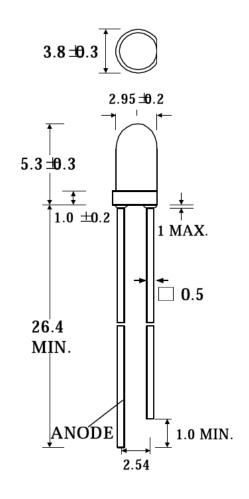
Features

*Emitting Color: Green

*High Luminous Intensity

*Technology: InGaAIP

*Peak Wavelength 563nm



Notes:

- 1. All Dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CL30G3D	InGaAlP	Green	Green Diffused	60°	





ABSOLUTE MAXIMUM RATINGS

TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Power Dissipation	Po	120	mW	
Pulse Current Forward Current	IFP	100	mA	
Continuous Forward Current	lF	50	mA	
Reverse Voltage	VR	5	V	
Operating Temperature Range	Topr	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	

IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

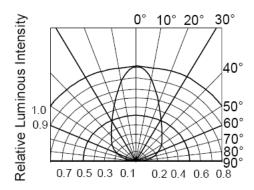
Darameter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	I _F = 20mA	330	500	-	mcd
Forward Voltage	VF	I⊧ = 20mA	1	2.0	2.4	V
Reverse Leakage Current	lr	V _R = 5V	1	-	10	μΑ
Viewing Angle	201/2	I⊧ = 20mA	1	60	ı	deg
Peak Wavelength	λ P	I⊧ = 20mA	1	563		nm
Dominant Wavelength	λ D	I⊧ = 20mA	1	560		nm

^{*}Tolerance of viewing angle: -10 / +5 deg.

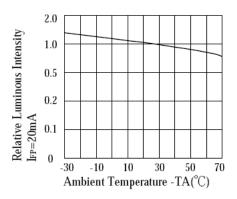




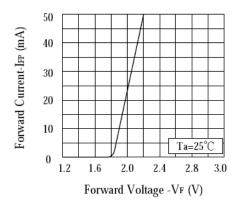
OPTICAL CHARACTERISTIC CURVES



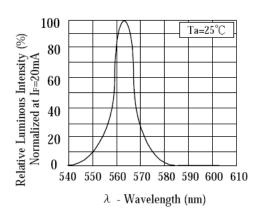
RADIATION DIAGRAM



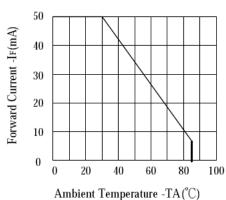
LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



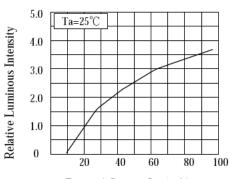
FORWARD CURRENT Vs. FORWARD VOLTAGE



RELATIVE LUMINOUS INTENSITY Vs. WAVELENGTH



MAX FORWARD CURRENT Vs. AMBIENT TEMPERATURE



Forward Current-IFP (mA)

LUMINOUS INTENSITY Vs. FORWARD CURRENT





SOLDERING CONDITIONS – LAMP TYPE LED

SOLDERING PROFILE

1. Iron:

Soldering Iron: 30W max Temperature 350 °C max

Soldering Time: 3 seconds max (one time)
Distance: 2mm min (from solder joint to body)

2. Wave Soldering Profile:

Dip soldering

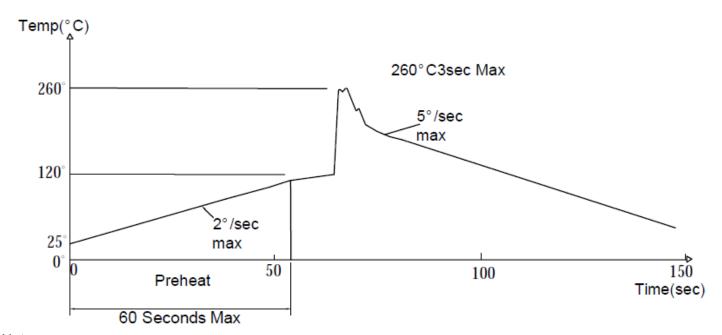
Preheat: 120 °C max

Preheat time: 120 seconds max

2 °C/sec (max)

Ramp-down: -5 °C/sec (max) Solder bath: 260 °C max Dipping time: 3 seconds max

Distance: 2mm min (from solder joint to body)



Notes:

- 1. Wave solder should not be made more than one time.
- 2. Only select one of the soldering conditions as above.

